

Product Data Sheet

Product	PSM-45
Productgroup	Peelable Solder Mask
Date	14-10-2010
Release	06.2

5	Especially made for this purpose
4	Generally qualified for this purpose
3	Generally usable, but not the best choice
2	Generally not usable for this purpose
1	Wrong choice

Post-cure removal	5
Pre-cure removal	2
Solder process	5
Selective conformal coating	3
No-Clean process	5
Post-solder cleaning	5
Amonia-free	2
OSP compatible	5
Ni/Au compatibel	3
Manual application	5
Dispensing	5
Printing	3
Plug-in components	4
Screw-fittings	4
Solvent/water sensitive components	3
Component shortage	5
Protects heat sensitive components	4
Fast skinning/curing @ 20 °C	5
Easy release from capillaries	5
Cosmetic cleanliness	5
ICCT compatible	5

Filmformer(s)	Latex
Color	Pink
Decomposition temperature [°C]	265.0
Solids content [% w/w]	69.01
pH as delivered	9.5
Odor	Mild Ammonia
Flashpoint COC [°C]	-
Viscosity @ 25°C [Pa's]	3.62
Cone/Plate	
Recommended film deposit [mm]	0.2
Coherent film [mm]	0.02
Skinning time 0.2 mm/20°C [min]	25.
Curing time 0.2 mm/20°C [min]	45.0
Max. curing temperature [°C]	65.
Max. hole diameter [mm]	3.
ISO-TS-16949 (IATF nummer)	0043973
Certificate of Compliance	Available
SPC-data*	Auditable
Environmental Load Unit**	10.76
VOC-content [% w/w]***	-
RoHS-Compliance Certificate	Available
Packaging	
Squeeze bottle (HDPE) [ml]	200
Wide neck drum (HDPE) [gram]	5000
Shelf-life (Weeks)	
Storage 4-10 [°C]	26.
Storage 20 [°C]	13.